



Customer Information Notification

202302010I : TJA1057 Datasheet Update

Note: This notice is NXP Company Proprietary.

Issue Date: Feb 17, 2023 **Effective date:** Mar 17, 2023

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For detailed information we invite you to [view this notification online](#)

Management summary

TJA1057 datasheet update

Change Category

- | | | | | |
|--|---|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Process | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Location | <input type="checkbox"/> Electrical spec./Test coverage |
- Firmware Other: Datasheet update

PCN Overview

Description

NXP Product Line In-Vehicle Networking (PL IVN) is updating the datasheet of product TJA1057. Two new product versions (TJA1057BT and TJA1057CT) have been added to the datasheet, textual and figure updates have been made and the allowed operating range has been expanded. No physical or design change has been made to the product, the improved/expanded specifications are achieved through updated conditions in the test program for TJA1057BT and TJA1057CT. For the other TJA1057 product versions the test program will be updated at a later moment in time, after which an updated PPAP Electrical Distribution (ED) report will become available.

The datasheet's revision history specifies the updates.

Attached to this Customer Information Notification (CIN) are three additional documents:

- A pdf document with detailed info on the datasheet update
- The applicable ZVEI Delta Qualification Matrix (DeQuMa) for this datasheet updates, both in zipped excel and pdf format. The applicable change ID numbers are SEM-DS-02 and SEM-DS-03
- The new TJA1057 datasheet, which will also be published on the NXP website (www.nxp.com) one month after the distribution of this CIN to customers

See the paragraphs 'Additional information' and 'Remarks' below for instructions on how to obtain these documents.

For the newly released TJA1057BT and TJA1057CT products a PPAP is available on request.

Reason

NXP PL IVN wants to properly inform you of the improved datasheet specifications for the TJA1057 product family.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

There is no impact on form, fit, function, reliability or quality, other than the intended improved datasheet specifications through tightened test limits.

Data Sheet Revision

A new datasheet will be issued

Additional information

Additional documents: [view online](#)

Remarks

Please use the link 'view online' under the heading 'Additional information' above, to log in to the NXP e-PCN system you're subscribed to, in order to obtain the attached document with relevant detailed information from the tab 'Files'.

Should you not be able to obtain this document, please contact your NXP sales representative or the e-mail address mentioned below under 'Contact and Support'.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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